



*AUTO EQUIPMENT
SOLUTION PROVIDER*

萬潤科技

AllRing Tech

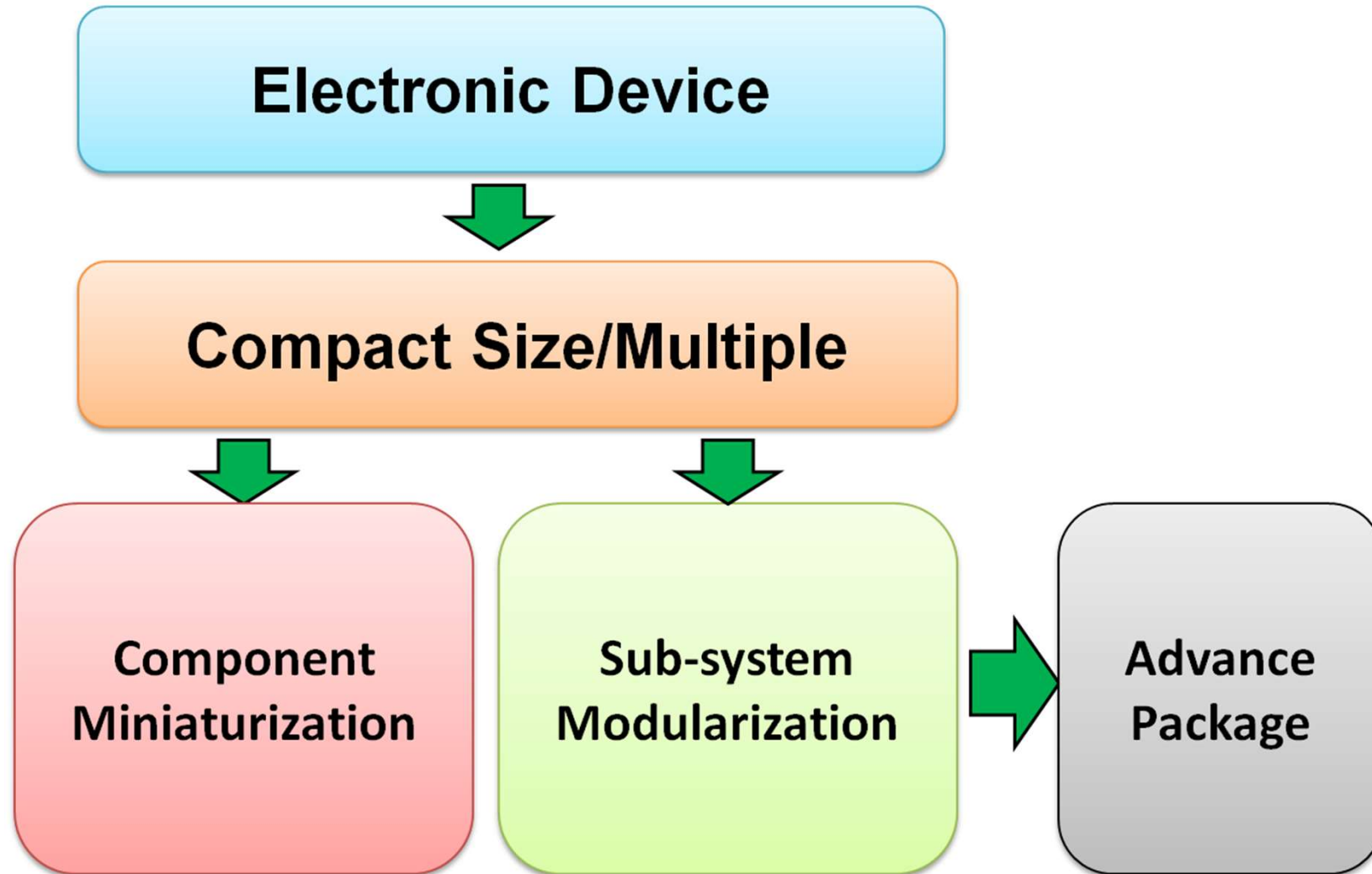
Stock Code:6187.TT



Company Profile

Established	May 24, 1996
Capital	NTD 833 Million (USD 27 Million)
Business	Automation equipment supplier for Semiconductor test & package, Passive Component manufacturing industries
Employee	222 (Mar, 2021)
Chairman	Larry Lu
Address	No.1 Luke 10th Rd. ,Lujhu,Kaohsiung,Taiwan
Website	www.allring-tech.com.tw

Industry Overview



Advance Package

Packaging Type		Manufacturer		Application
SIP (system in package)		OSAT	ASE	Smart phone IoT Mobile
			USI	
		Module house	Hon Hai	
			Luxshare	
		Component	AAC	
			AMS	
3D Package	InFO,CoWoS	Foundry	TSMC	Smart Phone IoT Mobile
	SoIC		TSMC	
Flip chip	2D/2.5D	OSAT	ASE	Smart Phone IoT Mobile
			Spil	
			Amkor	
			Chipbond	
			Powertech	

TSMC's 3D Fabric

TSMC 3DFabric™



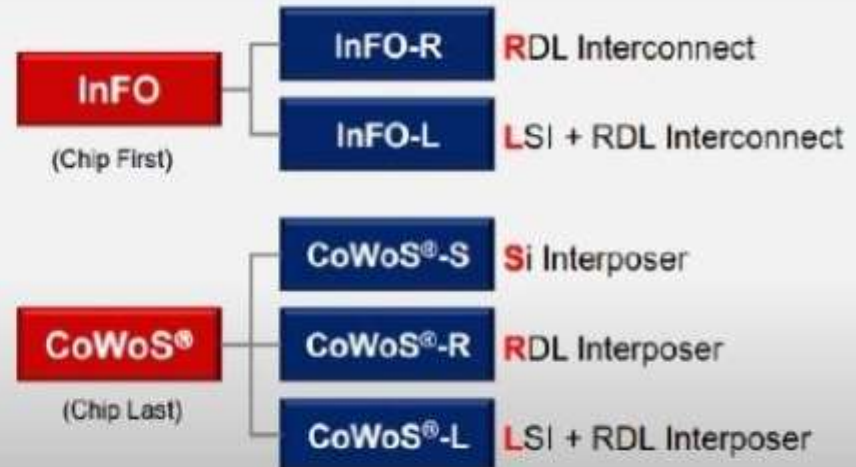
Chip Stacking (FE 3D)



SoIC: System on Integrated Chips

Source: TSMC

Advanced Packaging (BE 3D)



InFO: Integrated Fan-Out
CoWoS: Chip on Wafer on Substrate
RDL: Redistribution Layer
LSI: Local Si Interconnect



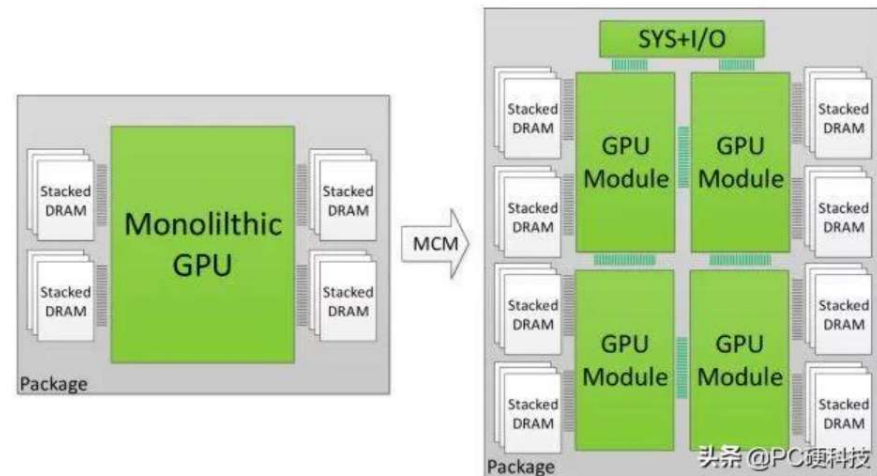
Advance Package

- Advanced packaging process
 - High Performance 2D with SoC & SoIC
 - Flip Chip – MCM(SiP)
 - (Multi-chip module; MCM)
 - 2.5D with SoC
 - COWOS
 - INFO
 - 3D with (SoIC & WoW)
 - COWOS
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Source: TSMC

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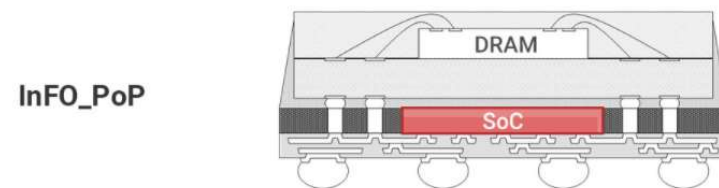
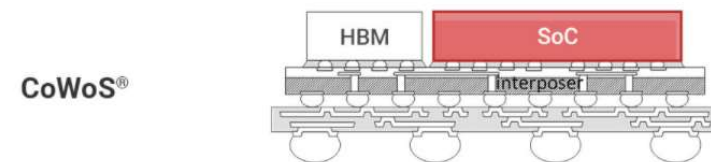


Source: TSMC

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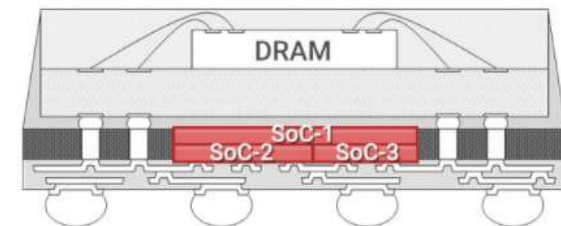
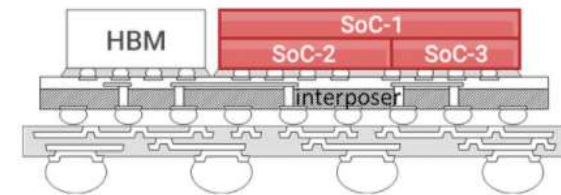
Source: TSMC



Advance Package

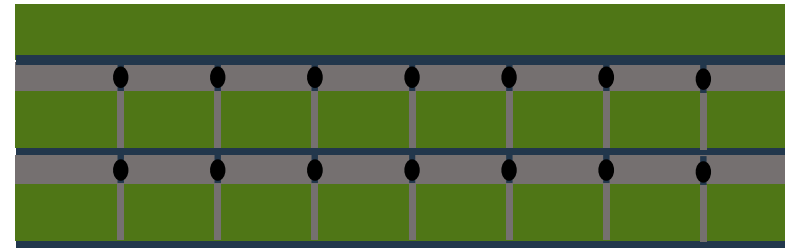
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Source: TSMC



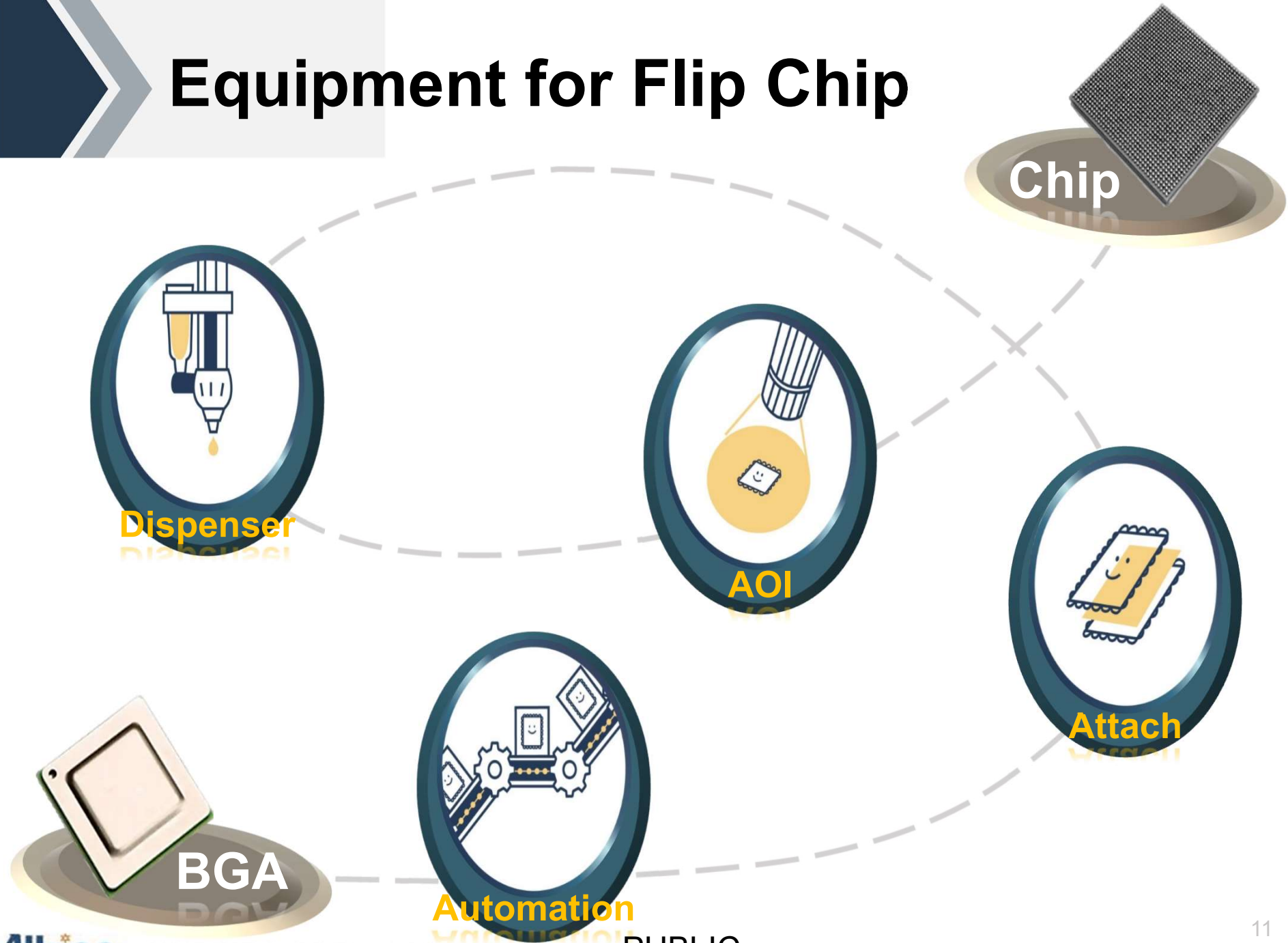
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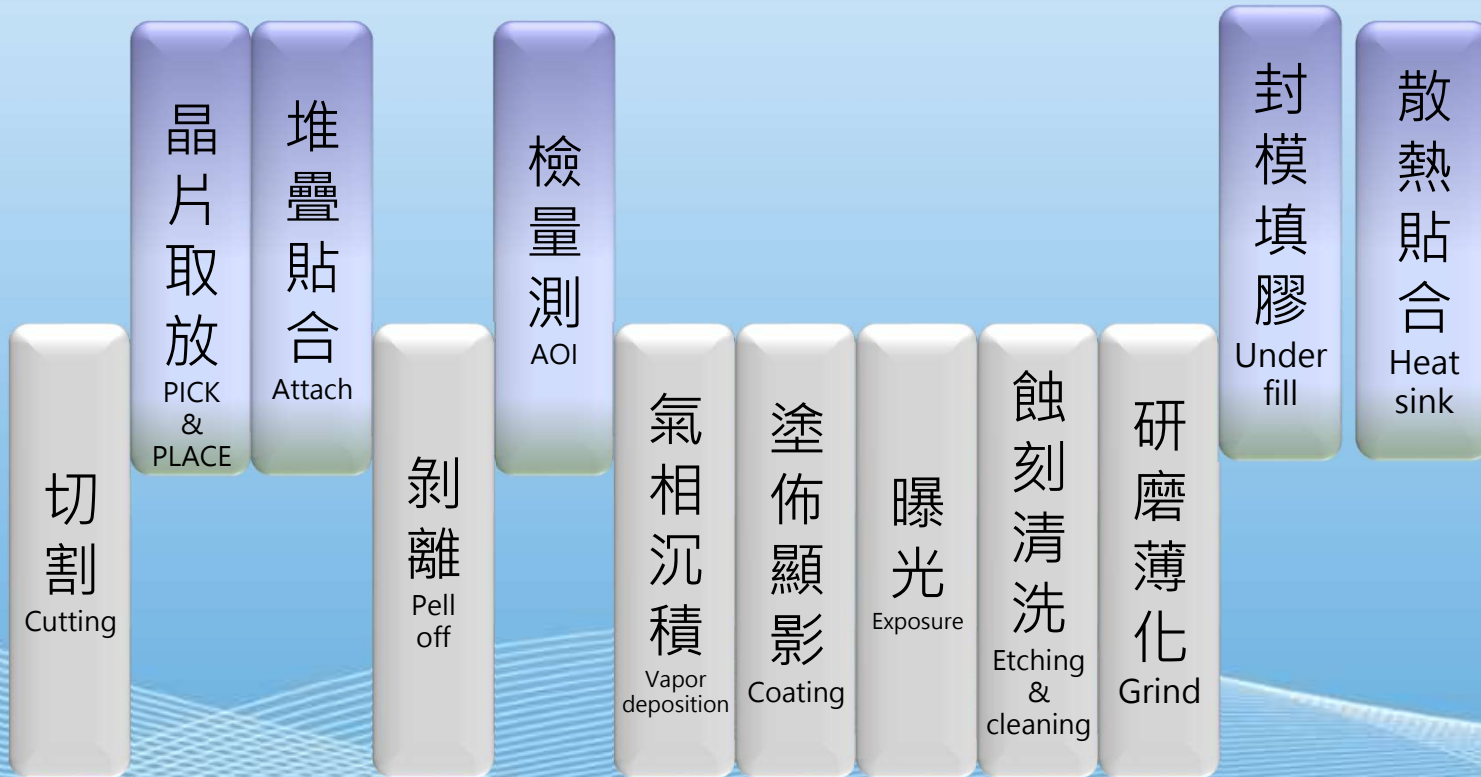


Source: TSMC

Equipment for Flip Chip



Allring in 3D Fabric Process

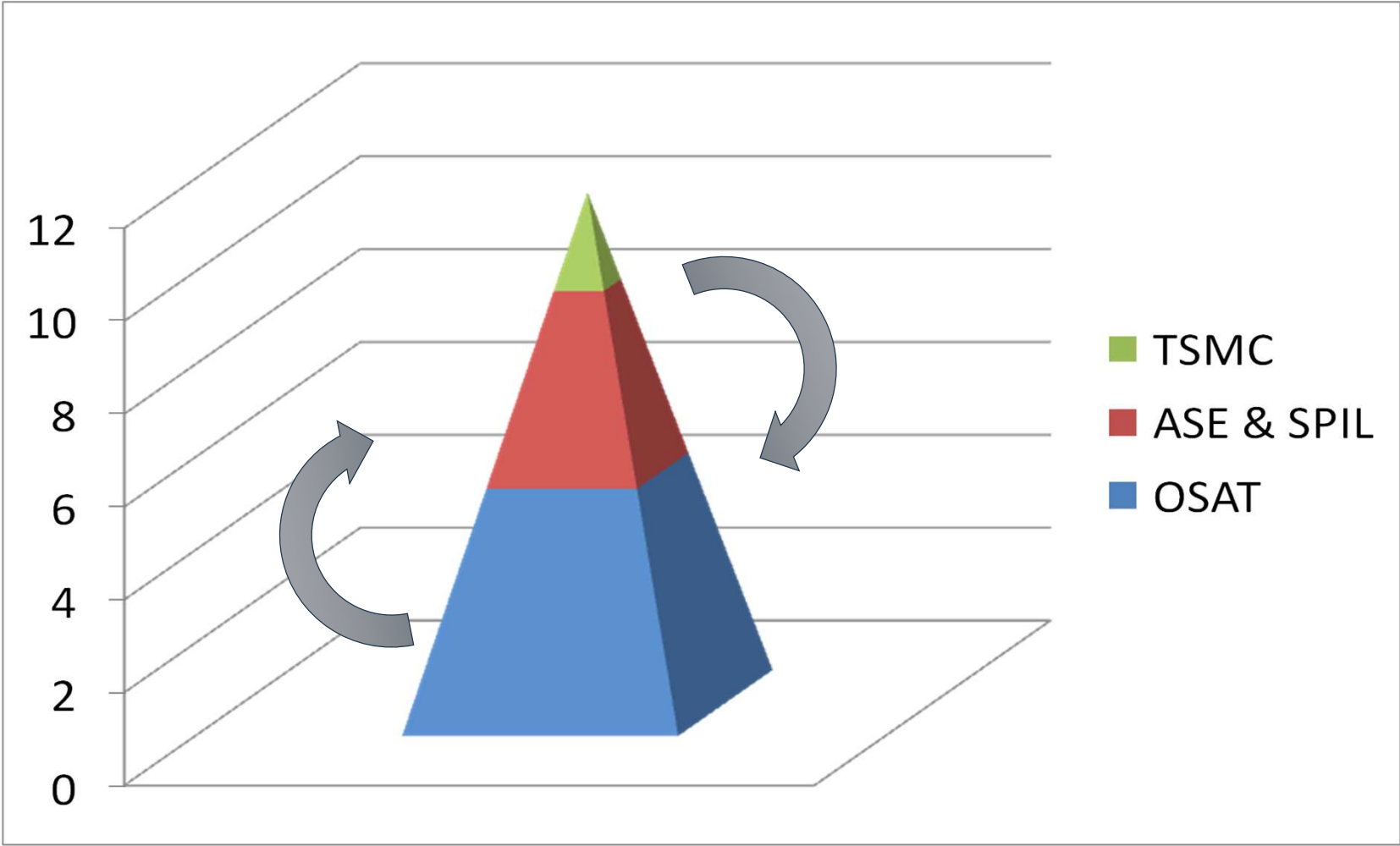




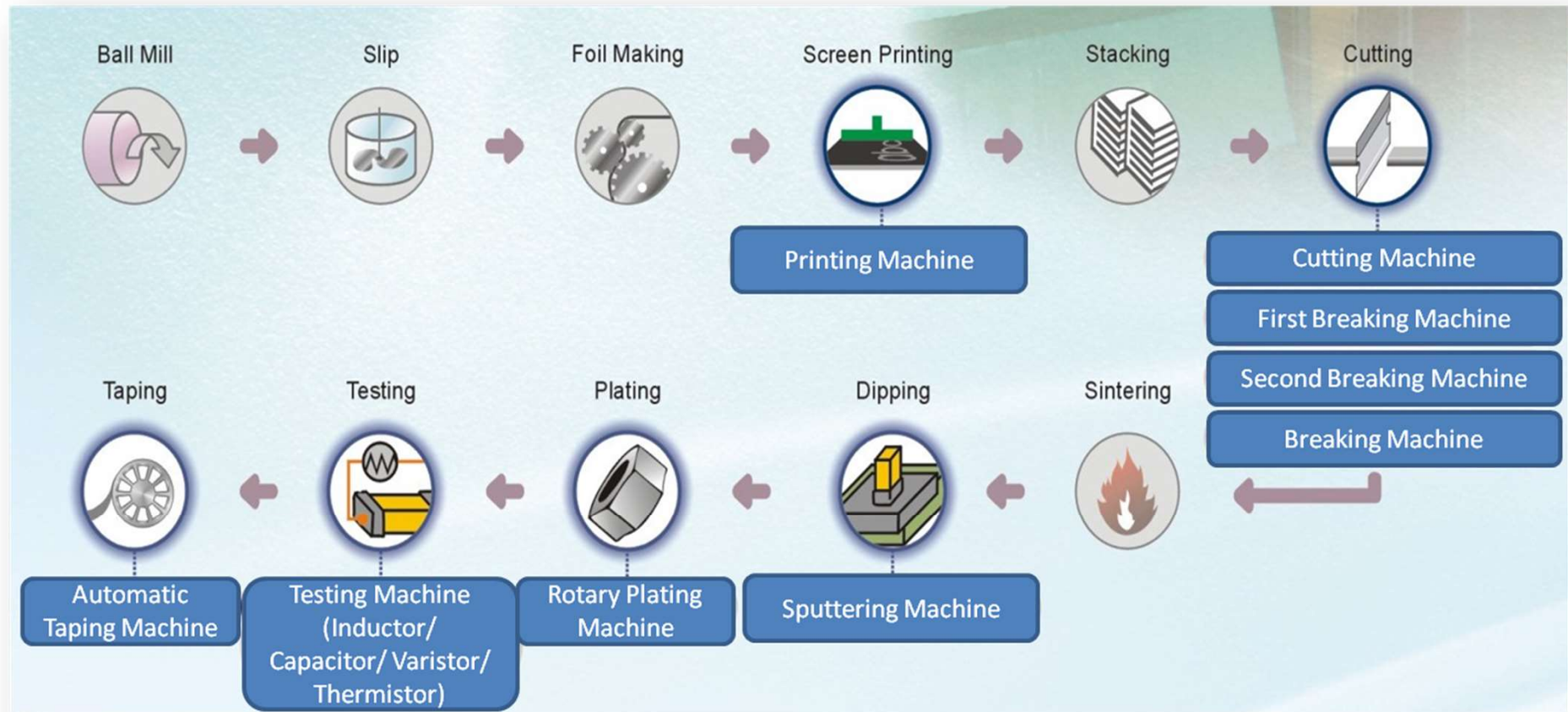
Roll of Allring

- Advanced packaging process
 - New Processing Tool(Technology Developing)
 - High performance Tool(Technology Developing)
- Unmanned factory
 - Rework
 - Inspection
 - Auto L/UL and Transfer
 - Sorter and Carrier Transfer
 - **No Alarm**
 - **Vender Service or Maintain**






Target



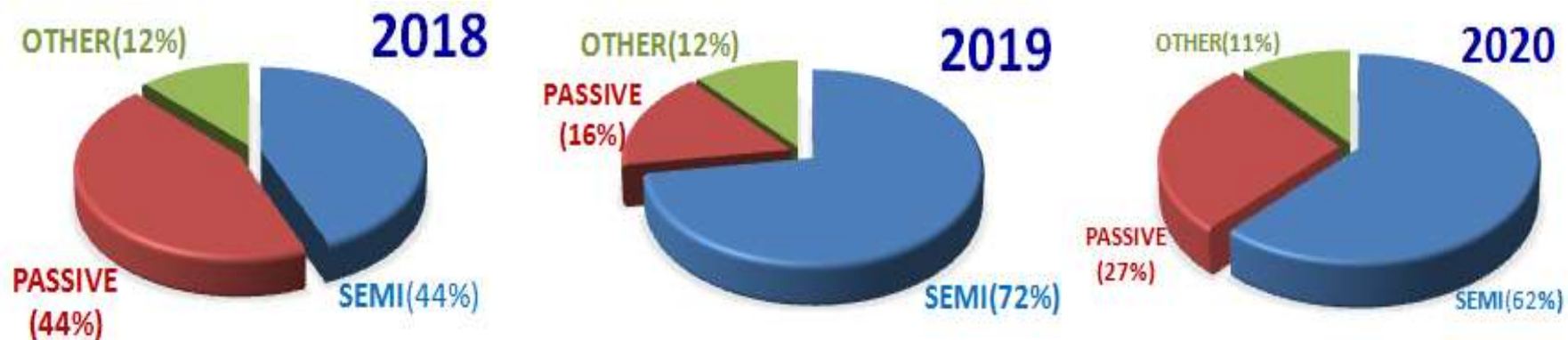
Passive Component Production Process



Customer Base

Semiconductor	Passive Component
       	            

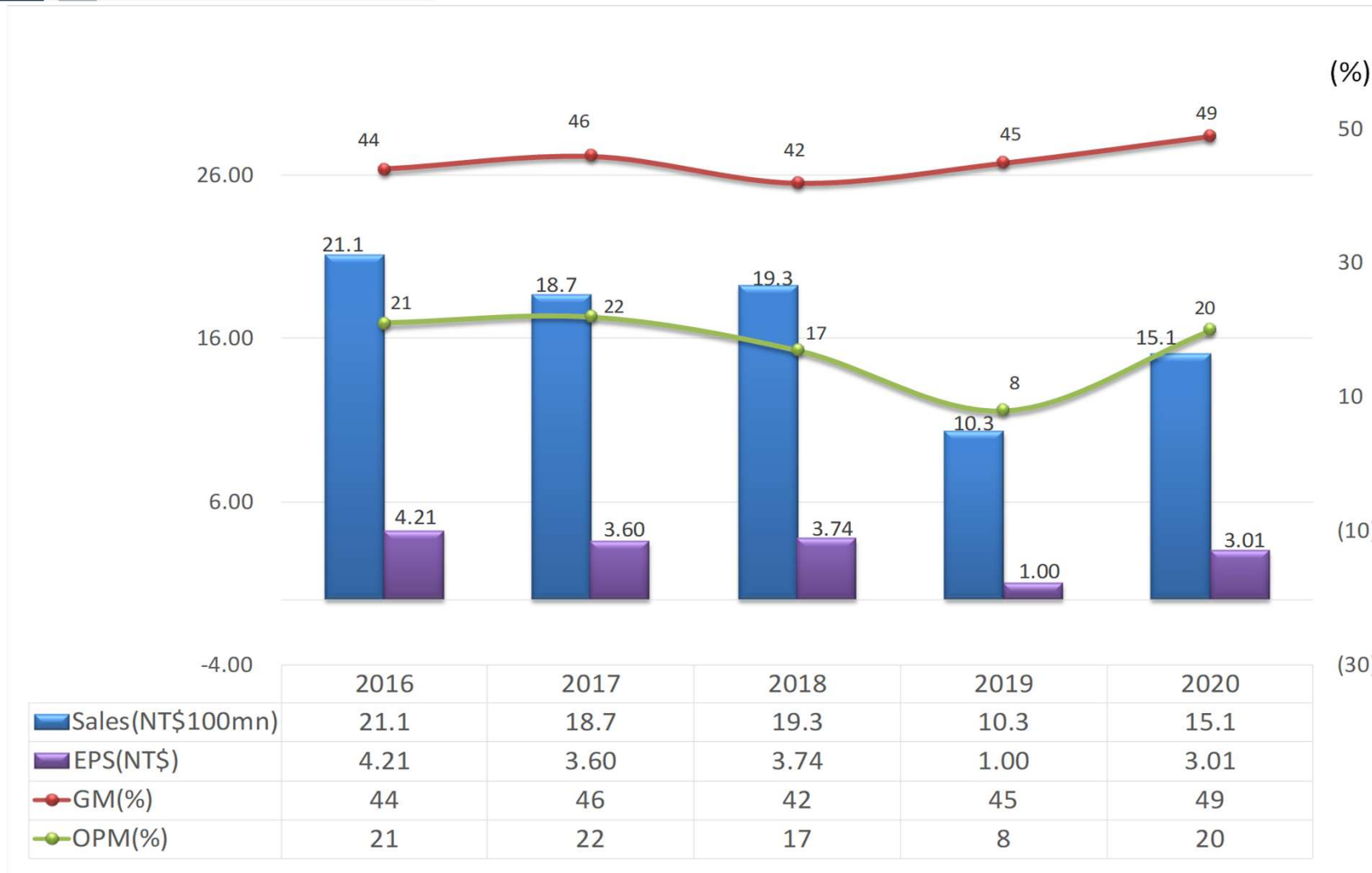
Revenue Breakdown



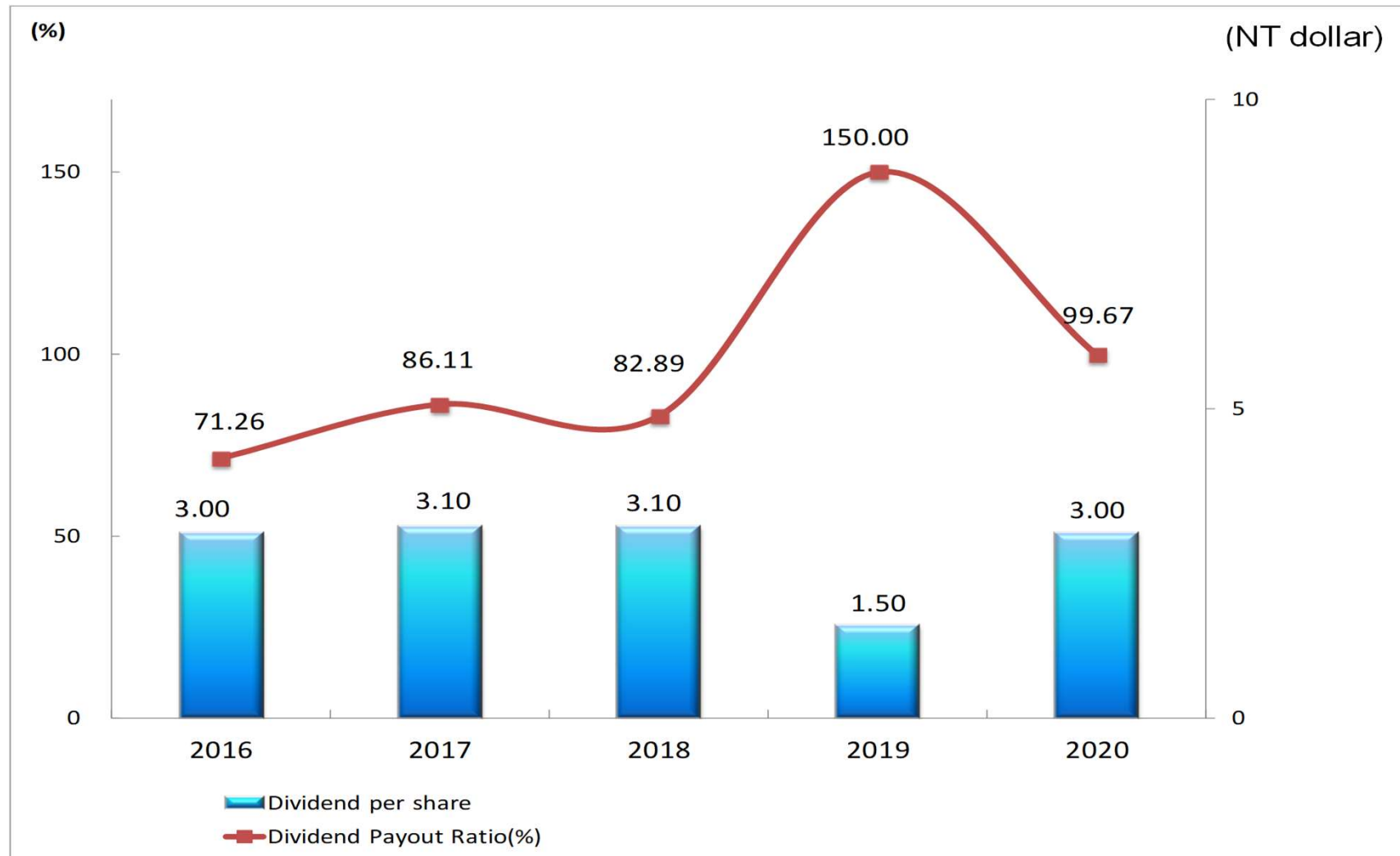
NT\$100M

	2018		2019		2020	
SEMI	8.46	44%	7.48	72%	9.28	62%
PASSIVE	8.49	44%	1.70	16%	4.14	27%
OTHER	2.31	12%	1.14	12%	1.64	11%
TOTAL	19.26	100%	10.32	100%	15.06	100%

Financial Highlights



Financial Highlights





Q & A



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